

VIRTUAL CONFERENCE Nov 16–19, 2020



Nov. 16

Chongzhe Gu: Damage Mechanism of the Acceleration of Intergranular Cracking of Stainless Steel SUS316LN Under Creep Loading at

Elevated Temperatures

Ryo Kikuchi : Molecular Dynamics Analysis of the Acceleration of Intergranular Cracking of Ni-Base Superalloy Caused by Accumulation of

Vacancies and Dislocations Around Grain Boundaries

Kenta Ishihara: Acceleration of Grain Boundary Cracking in Ni-Base Alloy 617 Under Creep-Fatigue Loading at 800°C

Nov. 17

Xiangyu Qiao: Development of a Strain-Controlled Graphene-Based Highly Sensitive Gas Sensor

Nov. 18

Qinqiang Zhang: A First Principle Study of Strain-induced Localized Electronic Properties of Dumbbell-shape Graphene Nanoribbon for Highly

Sensitive Strain Sensors

Genta Nakauchi: Microtexture Dependence of Mechanical and Electrical Properties of Gold Thin Films Used for Micro Bumps of 3D Stacking

Structures

Ken Suzuki : Crystallinity Dependence of Grain and Grain Boundary Strength of a Bicrystal Structure of Copper

Nov. 19

Hideo Miura : Degradation of the Strength of a Grain Boundary of Ni-Base Superalloys Under Creep-Fatigue Loading at Elevated Temperature

Shin Kasama: Non-Destructive Evaluation of the Degradation of Ni-Base Superalloy in the Air by Reflectance Spectrum Analysis

Yifan Luo : Quantitative Evaluation of the Dominant Factors of Intergranular Cracking of Ni-Base Superalloys Under Creep-Fatigue Loadings

at Elevated Temperature